

PATENT APPLICATION Attorney's Do. No. 9903-28

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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ADRIENNE CHOCHOLAK (SENDER'S PRINTED NAME)

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Box Patent Application

U. S. Patent and Trademark Office

P. O. Box 2327

Arlington, VA 22202

Enclosed for filing is a patent application under 37 CFR 1.53(b) of:

Inventor

Tae-Sub CHANG, Dong-Ho LEE and Min-Young SON:

For:

WAFER LEVEL PACKAGE INCLUDING GROUND METAL LAYER

Applicant requests FIG. 4A to be published with the application.

Enclosures:

- Specification (pages 1-7); claims (pages 8-10); abstract (page 11)
- SIX sheet(s) of FORMAL drawings
- Declaration or Combined Declaration and Power of Attorney
- Newly executed (original or copy)
- Assignment with cover sheet
 - Assignee Name and Address:

Samsung Electronics Co., Ltd.

Suwon-city, Kyungki-do, Korea

- Certified copy of priority document
- Return Postcard

<u>CLAIMS AS FILED</u>				
For	Number Filed	Number Extra	Rate	Basic Fee \$740
Total Claims	20-20	0	x \$ 18 =	0
Independent Claims	2-3	0	x \$ 84 =	0
TOTAL FILING FEE				\$740

PTO Form 2038 authorizing credit card payment for the above-listed fees is enclosed.



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Respectfully submitted,

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